

ABSTRACT

A semiconductor package and manufacturing method thereof are disclosed. The semiconductor package includes a substrate having an image sensor die, window, a glass, and solder balls. Not only the substrate having the window is attached to the upper side of the image sensor die, but also one side of the substrate extends and is bent so that the one side of the substrate is attached to the lower side of the image sensor die, thereby reducing the thickness and width of the semiconductor package. In another embodiment, at least one memory die can be stacked in an image sensor die or a substrate, so that the functions of the semiconductor package is growing multifarious and the package efficiency is increased.